

In the Claims:

1-10. (Cancelled).

11. (New) Circuit board, comprising:

at least one rigid area,

at least one flexible area,

a rigid individual layer which is provided with printed conductors or is copper-clad on at least one side,

an adhesive medium, and

at least one copper foil;

wherein the rigid area there being no flexible individual layer between the adhesive medium and the at least one copper foil in the flexible area, an insulating layer being applied directly to an inner side of the copper foil,

wherein the adhesive medium has recesses in the flexible area,

wherein, in the flexible area, there is no flexible individual layer between the rigid individual layer and the copper foil, and

wherein the insulating layer is a resist applied to the copper foil.

12. (New) Circuit board as claimed in claim 11, wherein the resist is a flexible solder resist .

13. (New) Circuit board as claimed in claim 1, wherein, at least in the flexible area, another insulating layer is applied to the outer side of the copper foil.

14. (New) Circuit board as claimed in claim 13, the other insulating layer is a resist which has been applied to the copper foil.

15. (New) Multi-layer circuit board with at least one rigid and at least one flexible area, comprising at least one circuit board according to claim 11, wherein there are several rigid individual layers which are provided with at least one of printed conductors or copper-cladding

on at least one side and several copper foils which are provided with an insulating layer in the flexible area, and wherein at least one of the rigid individual layers and the copper foils are cemented among one another.

16. (New) Process for producing rigid-flexible circuit boards with at least one rigid individual layer which is provided with printed conductors or is copper-clad on at least one side, with an adhesive medium and with at least one copper foil, the adhesive medium having recesses in the flexible area, comprising the steps of:

first, applying an uncured insulating layer to one side of the copper foil in the flexible area,

curing the insulating layer to such an extent that a free surface loses its adhesive capacity,

following the preceding steps, cementing the copper foil by means of the adhesive medium to the rigid individual layer and

then moving a piece from the rigid individual layer in the flexible area of the circuit board.

17. (New) Process as claimed in claim 16, wherein at least in the flexible area of the circuit board another insulating layer is applied to the outer side of the copper foil.

18. (New) Process as claimed in claim 17, wherein the insulating layers are applied to the copper foil by one of spraying, rolling or printing.

19. (New) Process as claimed in claim 16, wherein the insulating layer is applied to the copper foil by one of spraying, rolling or printing.